

Achieving Full System Signal Integrity for High Speed Backplane System

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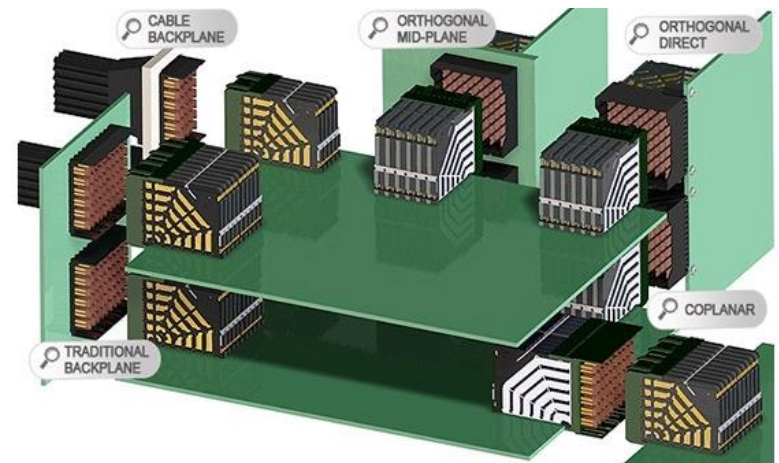


Outline

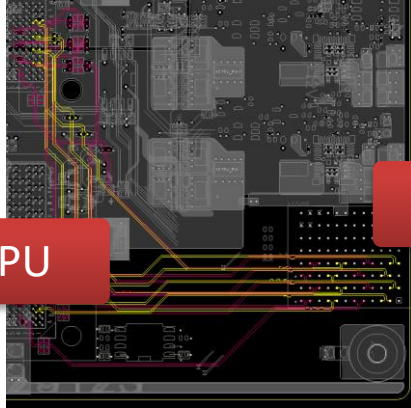
- Introduction of backplane system
- Challenge to backplane system simulation
- Components of EM simulation
- Analysis workflow
- Full backplane system SI simulation
- Summary

Backplane System

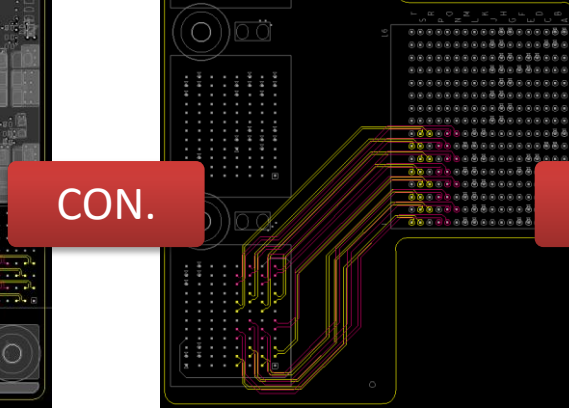
- Backplane system is used as a backbone to connect several printed circuit boards together to make up a complete system
- There are various configurations
 - Traditional backplane
 - Orthogonal direct
 - Orthogonal mid-plane
 - Coplanar
 - Cable backplane



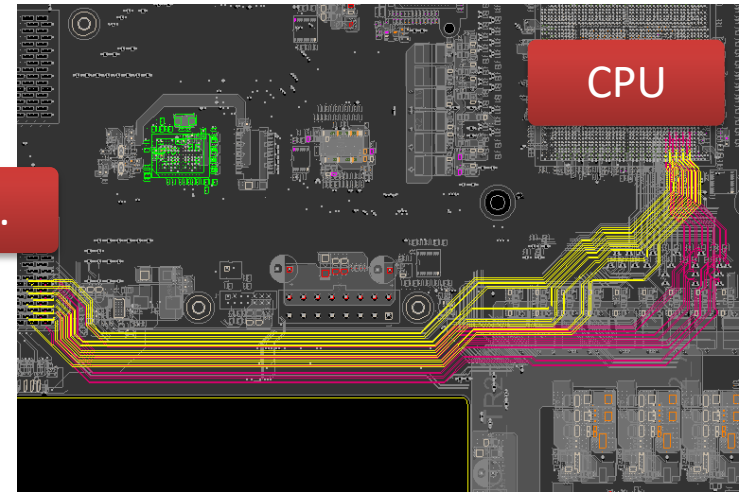
Backplane System Example -- Server Board



CPU Board

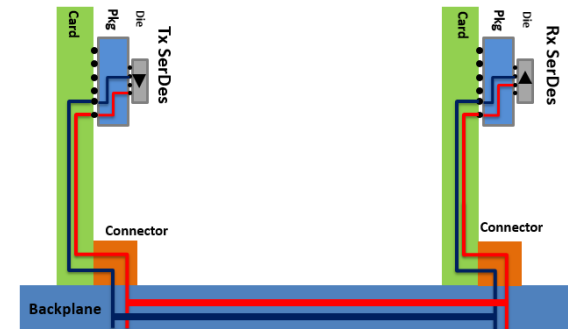


Backplane

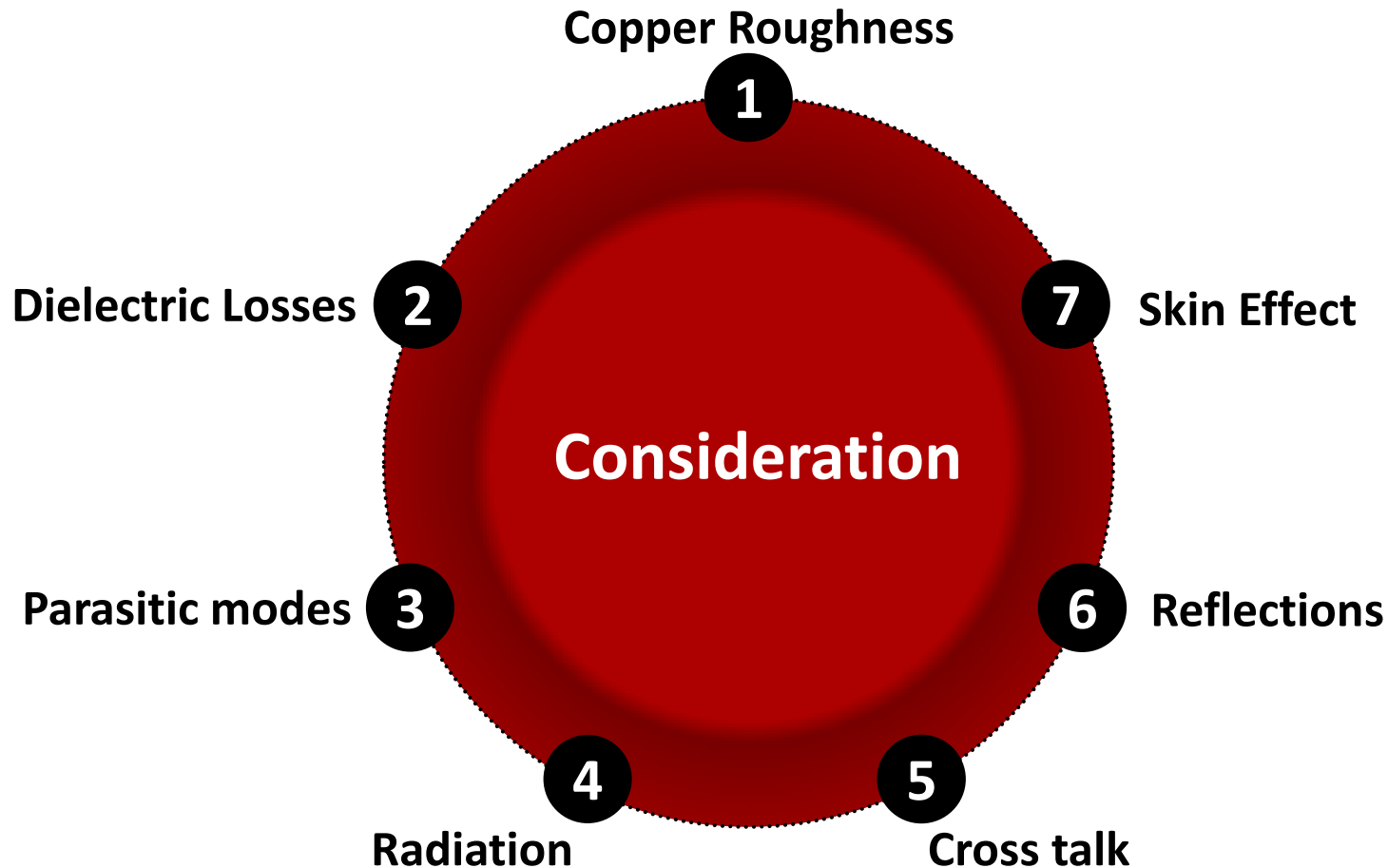


Switch Board

- Complex PCB layout.
- Maybe system has capacitor or repeater, Engineer need to check repeater gain based on channel's loss.



Backplane Design Consideration

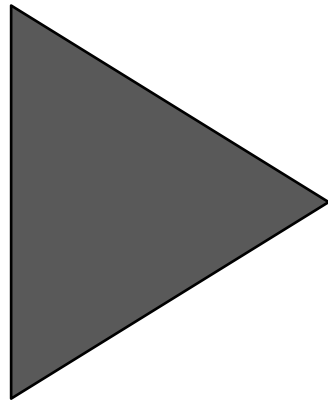


Challenges to Channel SI Simulation

- Reflection noise due to impedance mismatch, via, connector and other discontinuities.
- Need to capture all physical parasitic effects
 - Reflection, Coupling, Delay, Freq. dependent Losses,...
- Measurements become very difficult,
 - Parasitic values are small but important at high speed.
 - Large number of ports for interconnects.
- EM simulation of the discontinuities is a must. However, the current flow suffers the following problems:
 - Manual process to extract the via, trace, and other discontinuities
 - Manual process to build all the channels

Components of EM Simulation

✓ Transmitter



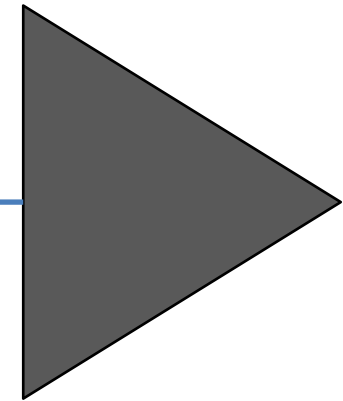
- Transistors
- Sources
- Algorithms
- Passives
- Memory

✓ Interconnect



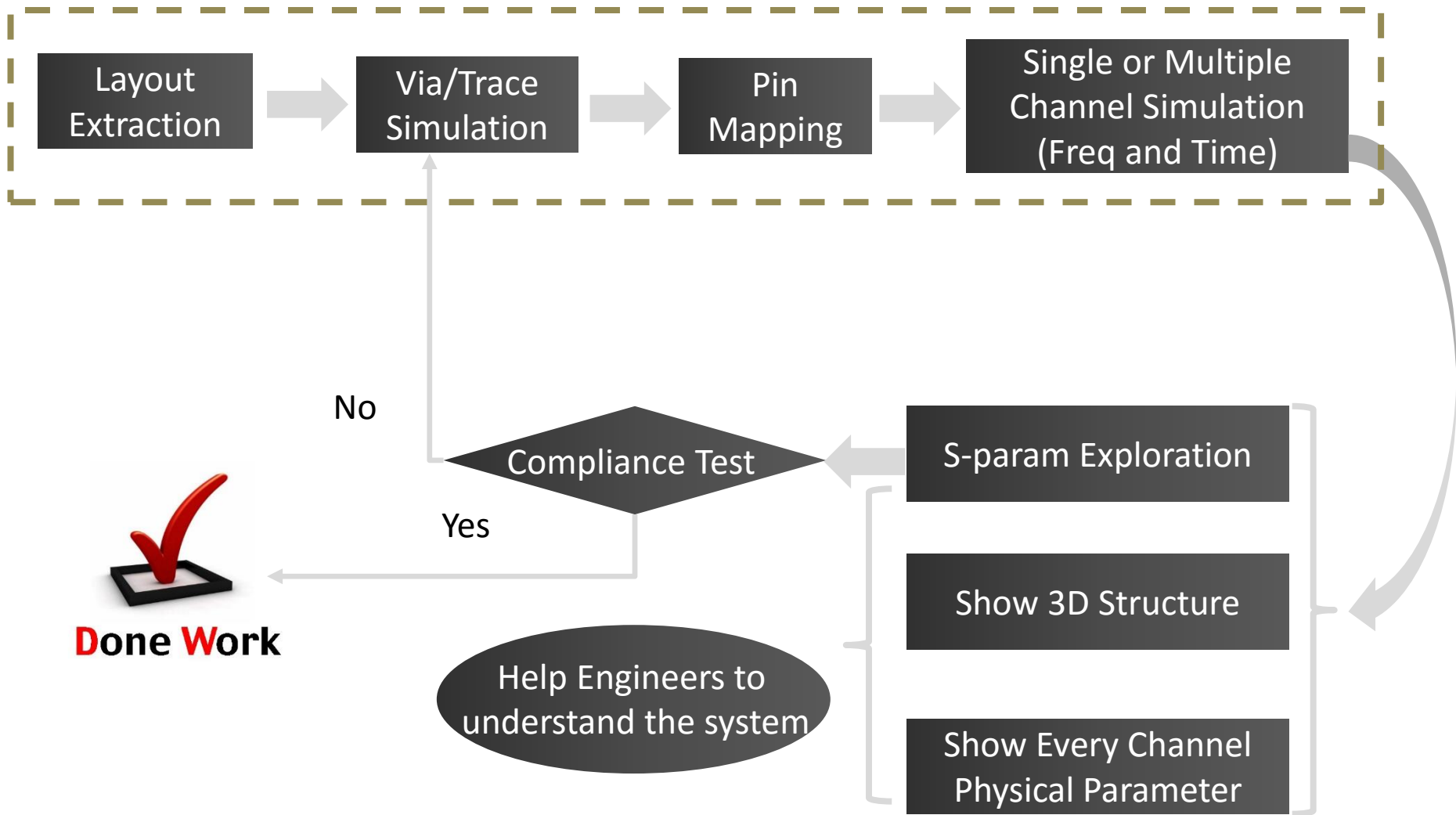
- **Thru Via**
- **BB Via**
- **Microstrip**
- **Stripline**
- **Capacitor**
- **Repeater**
- **Connector**
- **Backdrill**

✓ Receiver

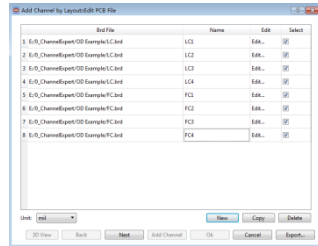


- Transistors
- Sources
- Passives
- Memory

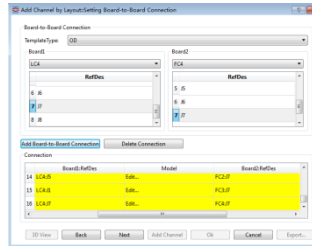
Analysis Workflow



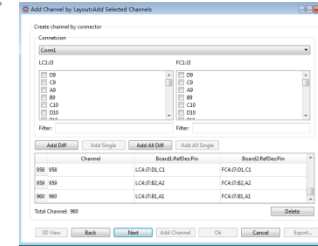
Analysis Workflow



**Import
Layout File**

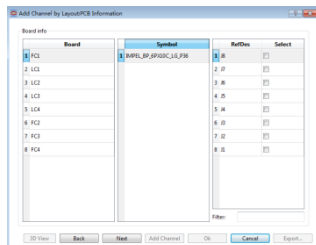


**Setting
Connection**

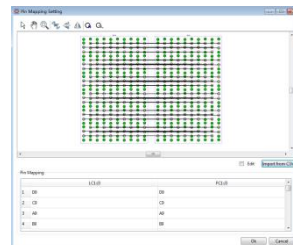


**Choose
Channel**

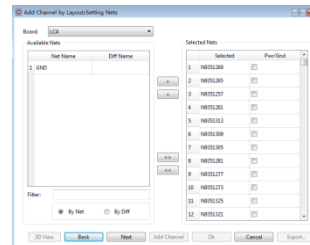
**Layout
Information**



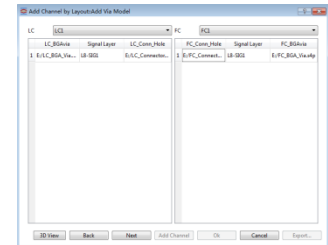
**Auto
Pin Mapping**



**Choose
Desired Net**



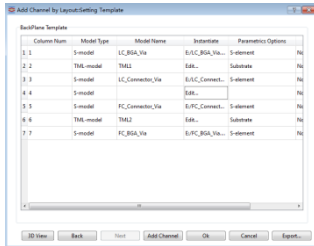
**Setting
Via Model**



Seamless Integration

Friendly User Interface

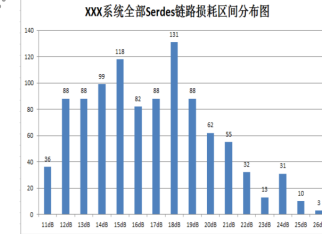
Analysis Workflow



● **Create Channel Table**

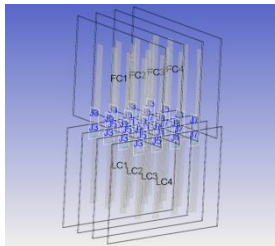


● **Create Excel File**

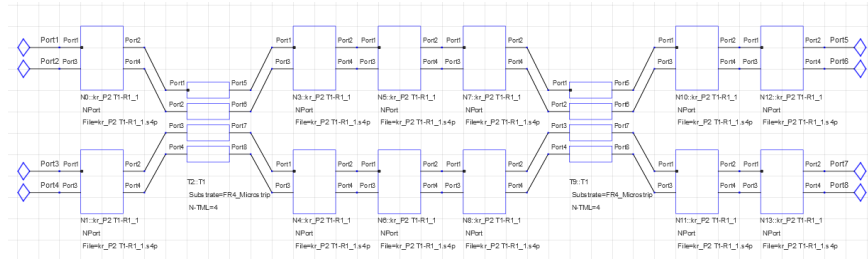


● **Batch Simulation**

● **Create 3D View**



● **Create Schematic**

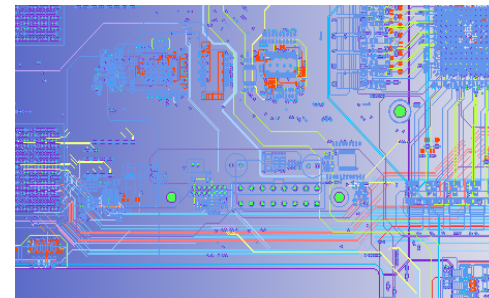
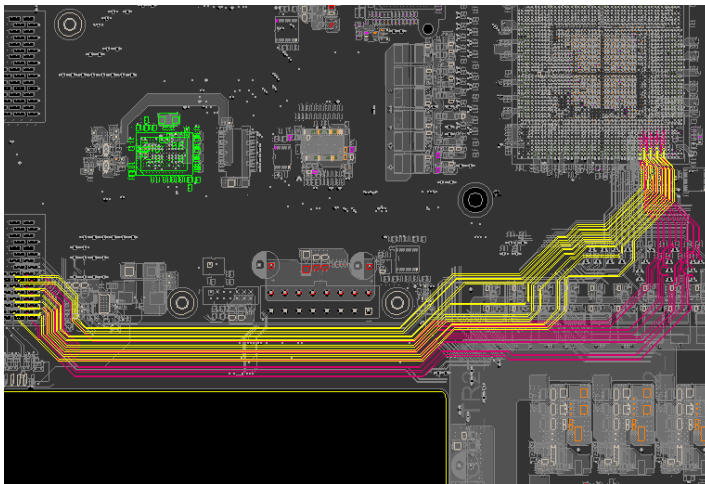


Time and frequency domain solutions

S-parameter, Crosstalk analysis, TDR, Eye diagrams

Post-Layout Extraction

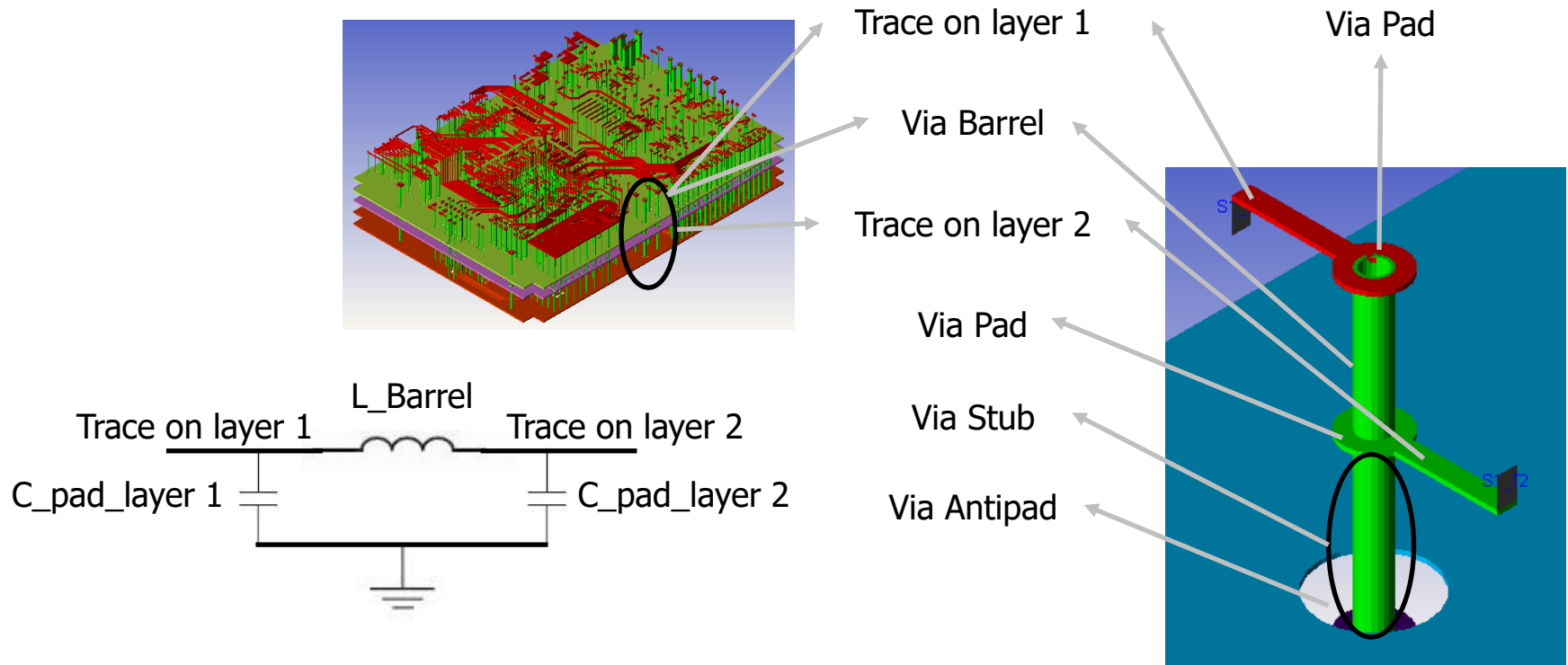
- Import all the boards for the backplane system
- Extract vias and traces from layout



- Layout Files
- Model Template

- Self cleaning process
- Discrete components
- Area/Net selection
- Stackup definition
- Materials definition
- BB, Back drill definition
- Auto port definition
- Parameter/Optimization
- High flexibility

3D Via Modeling



- Via and ground plane will lead to **parasitic capacitance** and **parasitic inductance**.
- ***How to deal with a lot of via models?***

Trace Modeling

- For trace, the common approach is to use 2D models for main high speed interconnect.

Edit Model Parameters

Parameter	Value
Substrate	FR4_Stripline
Name	TML1
N-TML	2
W1	3.5 mil
W2	3.5 mil
Angle	90
S1	13 mil
Length	1.0 inch

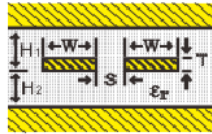
Substrate

☒ From Defined Substrate

FR4_Stripline

☐ From Defined Stackup

Signal Layer



Ok Cancel

Substrate Definition

Substrate Definition

Name: FR4_Stripline

Type: Stripline

Dielectric

H1 Dielectric Constant: 4.2 H1 Loss Tangent: 0.02

H2 Dielectric Constant: 4.2 H2 Loss Tangent: 0.02

Height(H1): 6 mil Debye(H1) Edit...

Height(H2): 6 mil Debye(H2) Edit...

Conductor

Conductor: Copper Conductivity: 5.8e+7 S/m Roughness...

Thickness(T): 1.2 mil


Trace Parametric By Default

Width(W): 3.5 mil

Spacing(S): 13 mil

Impedance

Zo: 105.348



Ok Cancel

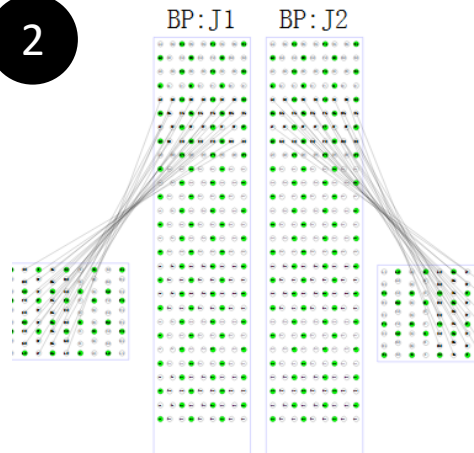
Connection between Boards through Pin Mapping

1

	DC1:J1	BP:J1	Net	BP:J2	DC2:J1
1	A5	A5	W30...	A5	A5
2	A7	A7	W30...	A7	A7
3	B5	B5	W30...	B5	B5
4	B6	B6	W30...	B6	B6
5	B7	B7	W30...	B7	B7
6	B8	B8	W30...	B8	B8
7	C6	C6	W30...	C6	C6
8	C8	C8	W30...	C8	C8
9	D5	D5	W30...	D5	D5
10	D7	D7	W30...	D7	D7

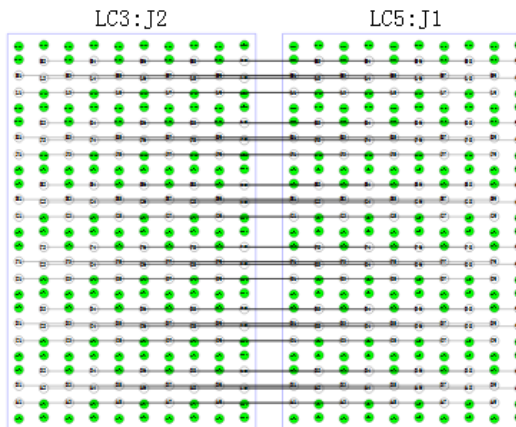
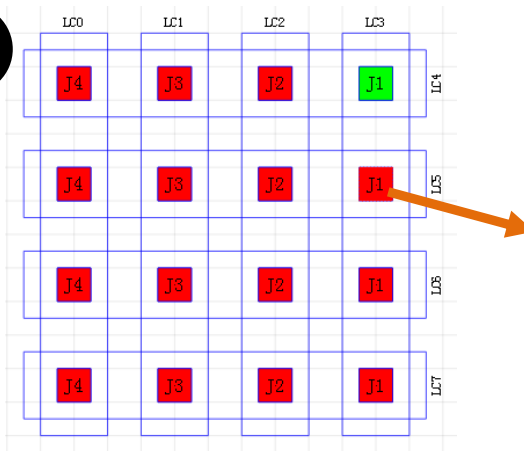
☐ Edit

2

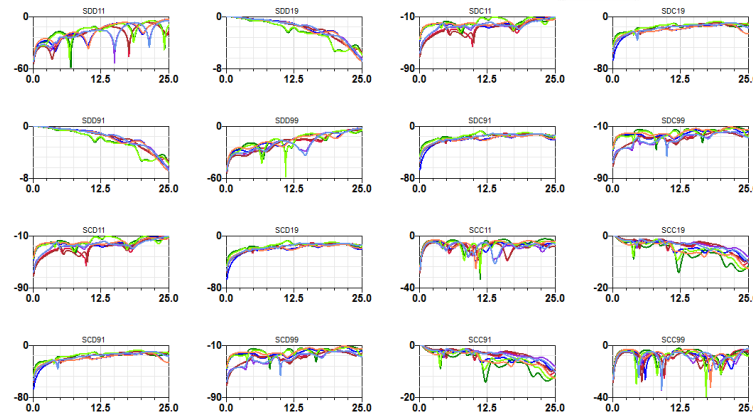
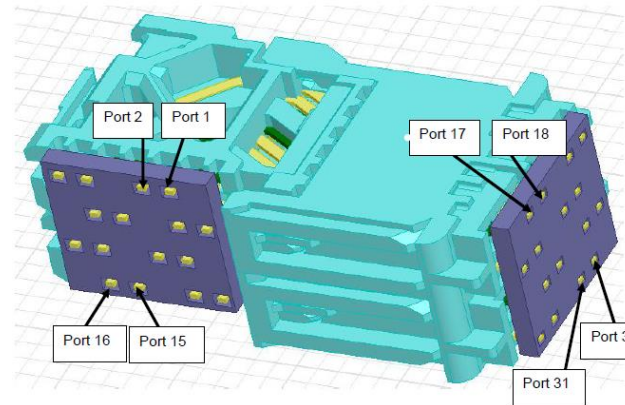
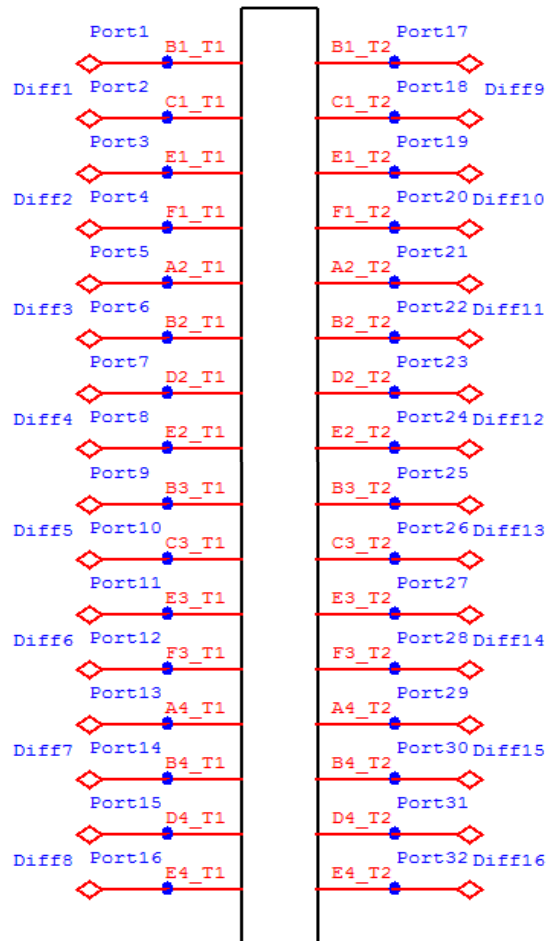


- Import .csv file.
- Create connection manually
- Create connection base on slot ID.

3

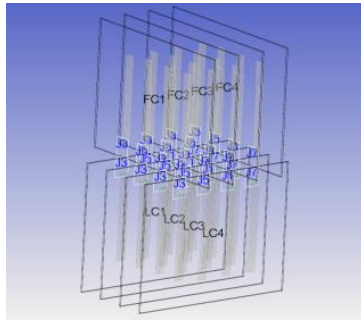


Connector S-parameter from Vendor

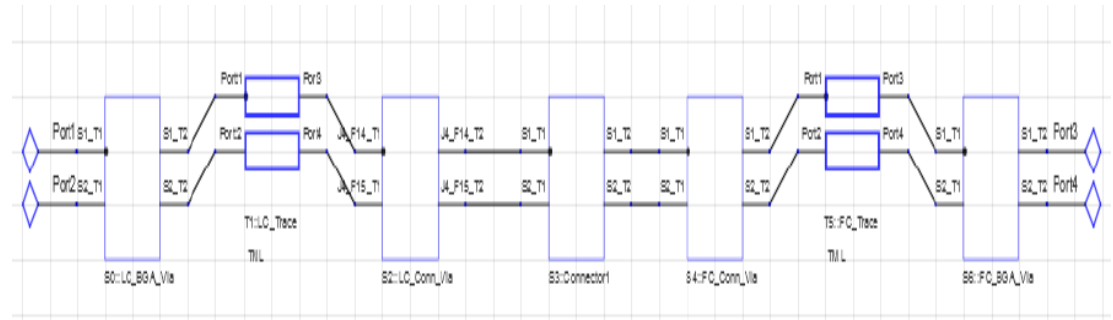


- Connector S-parameter file comes from vendor

Auto Cascading to Create Channel



Channelview



Cascading

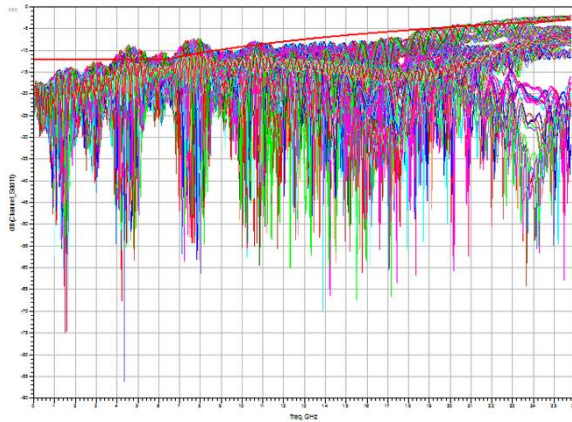
LC_Design	LC_Diff	LC_BGA_VIA	LC_Stackup	LC_layer	LC_Length	DiffLine	W	DiffLine	LC_CONN_VIA	Connector	FC_Design	FC_CONN_VIA	FC_Diff	FC_Stackup	FC_layer	FC_Length	DiffLine	W	DiffLine	FC_BGA_VIA	Total Length
LC0	0_Net1P/LC0_Net	E:\democase\antipad	LC0_Stackup	L8	1000	5	4	E:\democase\antipad	E:\democase\antipad	FC0	E:\democase\antipad	CO_Net1P/FC0_Net1	FC0_Stackup	L2	2000	6	5	E:\democase\antipad	3000		
LC1	0_Net2P/LC0_Net	E:\democase\antipad	LC1_Stackup	L8	1500	5	4	E:\democase\antipad	E:\democase\antipad	FC1	E:\democase\antipad	CO_Net2P/FC0_Net2	FC1_Stackup	L6	3000	6	5	E:\democase\antipad	4500		
LC2	0_Net3P/LC0_Net	E:\democase\antipad	LC2_Stackup	L8	1500	5	4	E:\democase\antipad	E:\democase\antipad	FC2	E:\democase\antipad	CO_Net3P/FC0_Net3	FC2_Stackup	L6	3000	6	5	E:\democase\antipad	4500		
LC3	0_Net4P/LC0_Net	E:\democase\antipad	LC3_Stackup	L8	1500	5	4	E:\democase\antipad	E:\democase\antipad	FC3	E:\democase\antipad	CO_Net4P/FC0_Net4	FC3_Stackup	L6	3000	6	5	E:\democase\antipad	4500		
LC4	0_Net5P/LC0_Net	E:\democase\antipad	LC4_Stackup	L8	1500	5	4	E:\democase\antipad	E:\democase\antipad	FC4	E:\democase\antipad	CO_Net5P/FC0_Net5	FC4_Stackup	L6	3000	6	5	E:\democase\antipad	4500		
LC5	0_Net6P/LC0_Net	E:\democase\antipad	LC5_Stackup	L8	1500	5	4	E:\democase\antipad	E:\democase\antipad	FC5	E:\democase\antipad	CO_Net6P/FC0_Net6	FC5_Stackup	L6	3000	6	5	E:\democase\antipad	4500		
LC6	0_Net7P/LC0_Net	E:\democase\antipad	LC6_Stackup	L8	1500	5	4	E:\democase\antipad	E:\democase\antipad	FC6	E:\democase\antipad	CO_Net7P/FC0_Net7	FC6_Stackup	L6	3000	6	5	E:\democase\antipad	4500		
LC7	0_Net8P/LC0_Net	E:\democase\antipad	LC7_Stackup	L8	1500	5	4	E:\democase\antipad	E:\democase\antipad	FC7	E:\democase\antipad	CO_Net8P/FC0_Net8	FC7_Stackup	L6	3000	6	5	E:\democase\antipad	4500		

Excel File

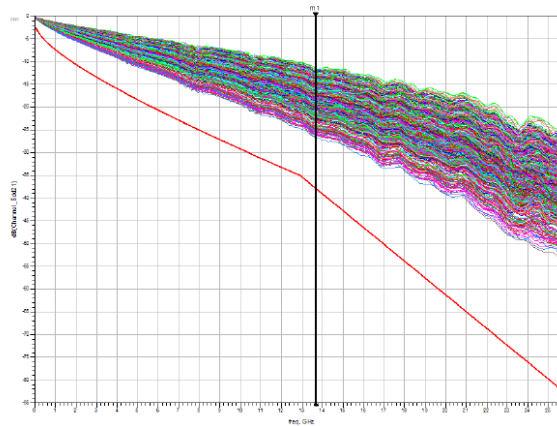
- 3D structure of BP system
- Hide/Show board or net in 3D
- Show entire channel path
- Single vs. multiple simulation and cascading
- Fast and memory efficient
- Show channel's structure size in Excel file
- Easily find worst channel
- Easily generate Excel report

Full Backplane SI Simulation - Frequency Domain

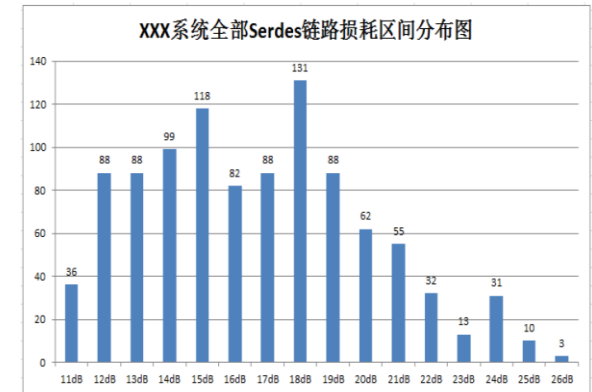
- Full backplane SI simulation is achieved by sweeping all the channels



Full Net Return Loss

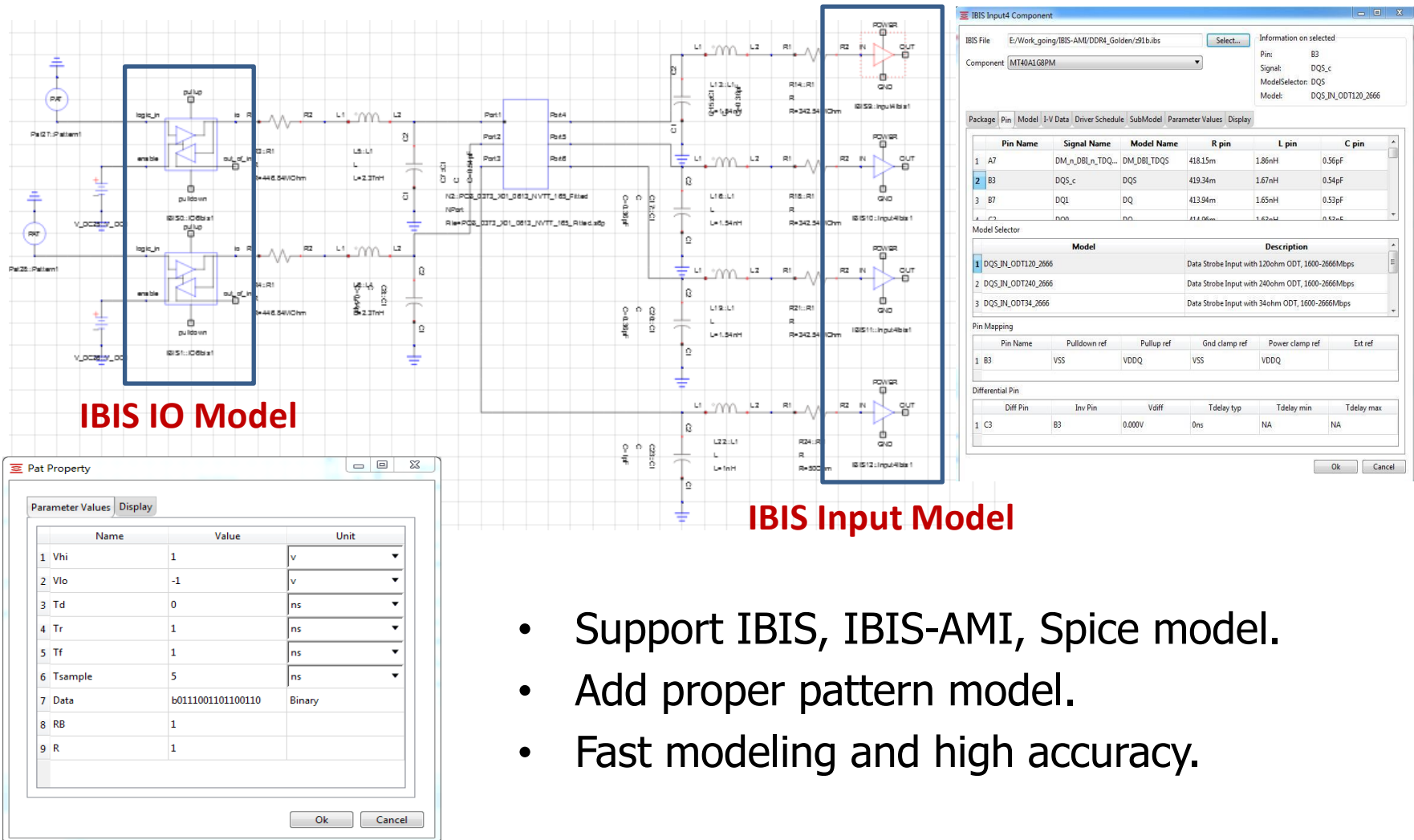


Full Net Insertion Loss



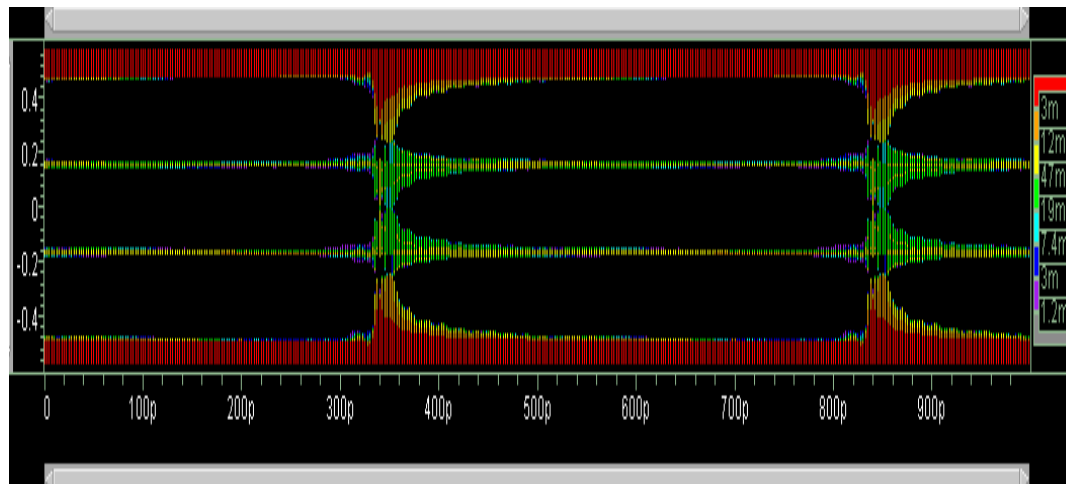
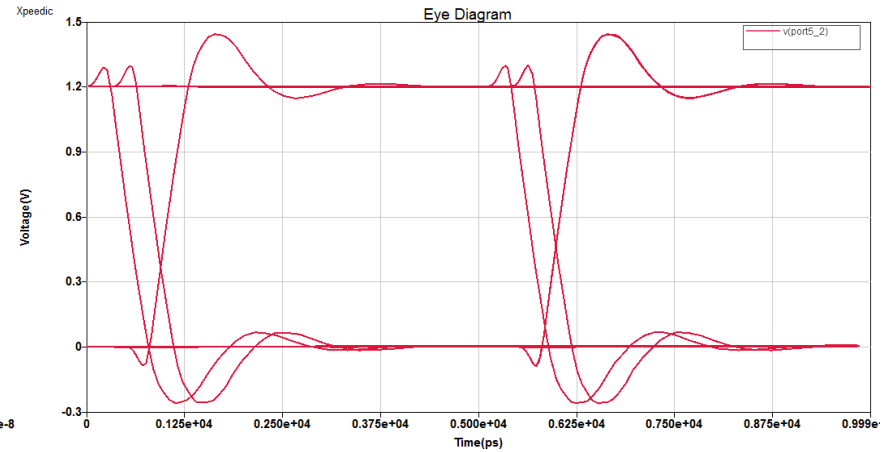
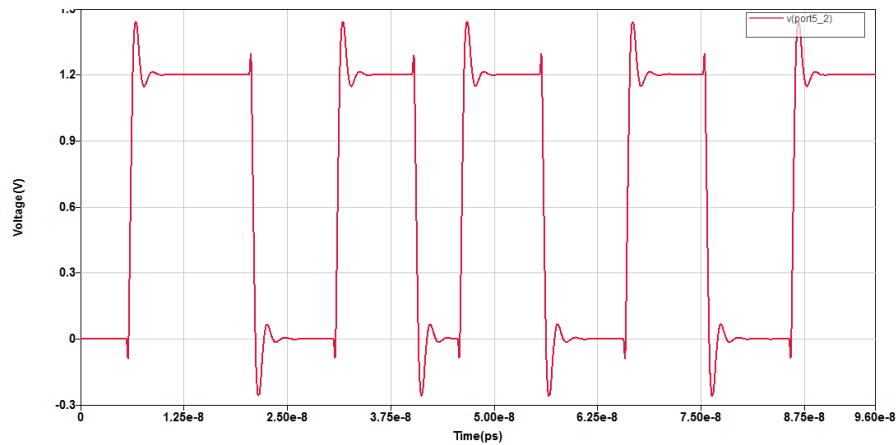
Net Distribution @ 13.67 GHz

Full Backplane SI Simulation - Time Domain



- Support IBIS, IBIS-AMI, Spice model.
- Add proper pattern model.
- Fast modeling and high accuracy.

Full Backplane SI Simulation - Time Domain



Summary

- Passive channel modeling and simulation is essential to high speed channel design.
- Optimal channel design requires user friendly EDA tool to do layout extraction, via optimization, trace simulation, S-parameter cascading, S-parameter exploration, etc.
- Full backplane system SI simulation is achieved by sweeping all the channels with correct models.

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